

MSG36E31

SiGe HBT type

For low-noise RF amplifier

■ Features

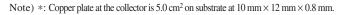
- Compatible between high breakdown voltage and high cut-off frequency
- Low noise, high-gain amplification
- Two elements incorporated into one package (Each transistor is separated)
- Reduction of the mounting area and assembly cost by one half

Basic Part Number

• MSG33003 + MSG33001

■ Absolute Maximum Ratings $T_a = 25$ °C

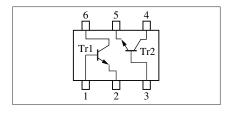
	Parameter	Symbol	Rating	Unit
Tr1	Collector-base voltage (Emitter open)	V _{CBO}	9	V
	Collector-emitter voltage (Base open)	V _{CEO}	6	V
	Emitter-base voltage (Collector open)	V _{EBO}	1	V
	Collector current	I_{C}	100	mA
Tr2	Collector-base voltage (Emitter open)	V _{CBO}	9	V
	Collector-emitter voltage (Base open)	V _{CEO}	6	V
	Emitter-base voltage (Collector open)	V _{EBO}	1	V
	Collector current	I_C	30	mA
Overall	Total power dissipation *	P_{T}	125	mW
	Junction temperature	T_j	125	°C
	Storage temperature	T _{stg}	-55 to +125	°C



Unit: mm 0.12 \(\frac{10.03}{0.02} \) \(\frac{1}{0.002} \) \(\

Marking Symbol: 7D

Internal Connection



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■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

• Tr1

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 9 \text{ V}, I_{E} = 0$			1	μΑ
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = 6 \text{ V}, I_{B} = 0$			1	μΑ
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = 1 \text{ V}, I_C = 0$			1	μΑ
Forward current transfer ratio	h _{FE}	$V_{CE} = 3 \text{ V}, I_{C} = 10 \text{ mA}$	100		220	_
Transition frequency *	f_T	$V_{CE} = 3 \text{ V}, I_{C} = 30 \text{ mA}, f = 2 \text{ GHz}$		19		GHz
Forward transfer gain *	S _{21e} 2	$V_{CE} = 3 \text{ V}, I_{C} = 30 \text{ mA}, f = 2 \text{ GHz}$	7.0	10.0		dB
Noise figure *	NF	$V_{CE} = 3 \text{ V}, I_{C} = 10 \text{ mA}, f = 2 \text{ GHz}$		1.4	2.0	dB
Collector output capacitance	C _{ob}	$V_{CB} = 3 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$		0.5	0.8	pF
(Common base, input open circuited) *						

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

- 2. Observe precautions for handling. Electrostatic sensitive devices.
- 3. *: Verified by random sampling



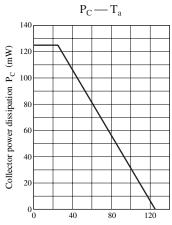
■ Electrical Characteristics (continued) $T_a = 25$ °C ± 3 °C

• Tr2

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 9 \text{ V}, I_{E} = 0$			1	μΑ
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = 6 \text{ V}, I_{B} = 0$			1	μΑ
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = 1 \text{ V}, I_C = 0$			1	μΑ
Forward current transfer ratio	h _{FE}	$V_{CE} = 3 \text{ V}, I_{C} = 3 \text{ mA}$	100		220	_
Transition frequency *	f_T	$V_{CE} = 3 \text{ V}, I_{C} = 10 \text{ mA}, f = 2 \text{ GHz}$		19		GHz
Forward transfer gain *	S _{21e} 2	$V_{CE} = 3 \text{ V}, I_{C} = 10 \text{ mA}, f = 2 \text{ GHz}$	9.0	11.0		dB
Noise figure *	NF	$V_{CE} = 3 \text{ V}, I_{C} = 3 \text{ mA}, f = 2 \text{ GHz}$		1.4	2.0	dB
Collector output capacitance	C _{ob}	$V_{CB} = 3 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$		0.3	0.6	pF
(Common base, input open circuited) *						

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.
 - 2. Observe precautions for handling. Electrostatic sensitive devices.
 - 3. *: Verified by random sampling

Common characteristics chart

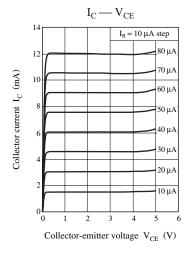


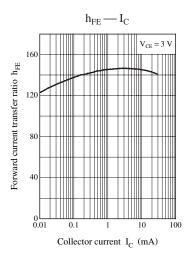
Ambient temperature T_a (°C)

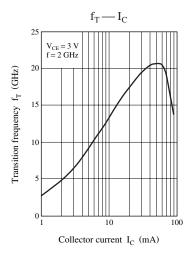
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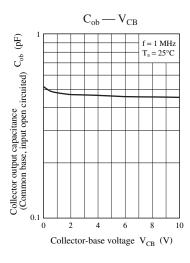
Panasonic

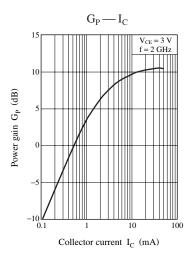
Characteristics charts of Tr1

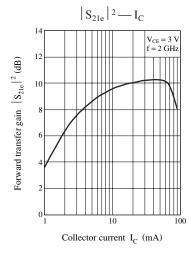


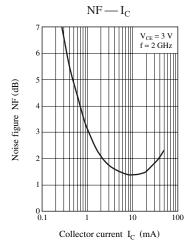


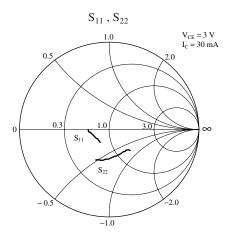




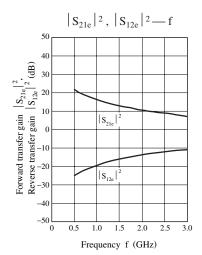






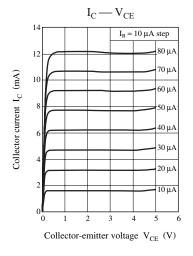


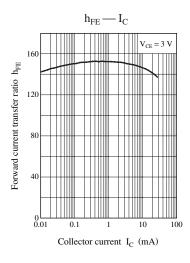
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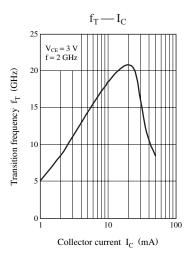


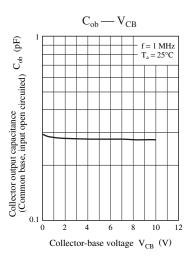
Panasonic

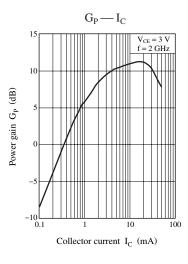
Characteristics charts of Tr2

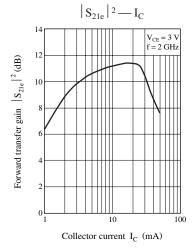


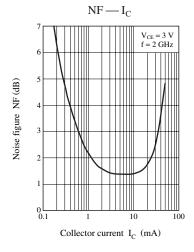


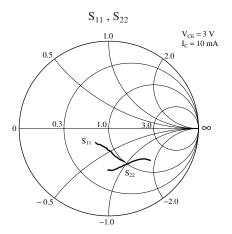




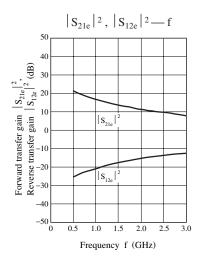








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